Roughly 150 sqm bonding facility cleanroom available

PICTURE OF THE IPE CLEANROOM

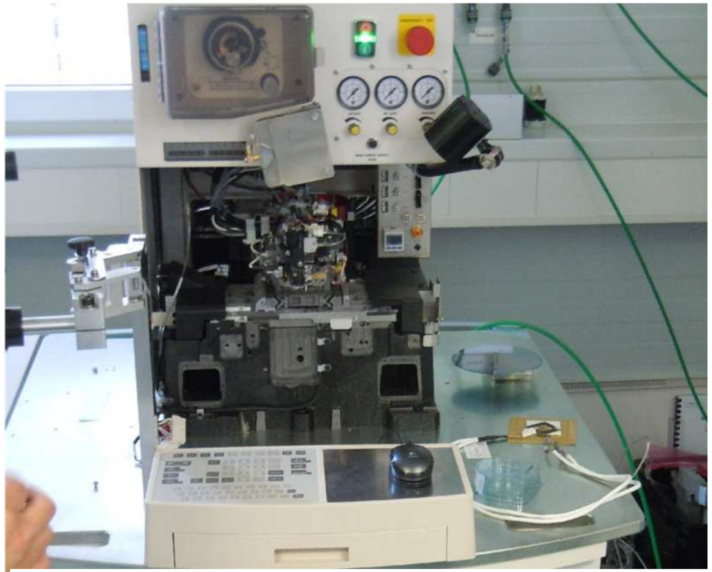
Flip-chip bonding system achieves ~ 7 µm placement accuracy

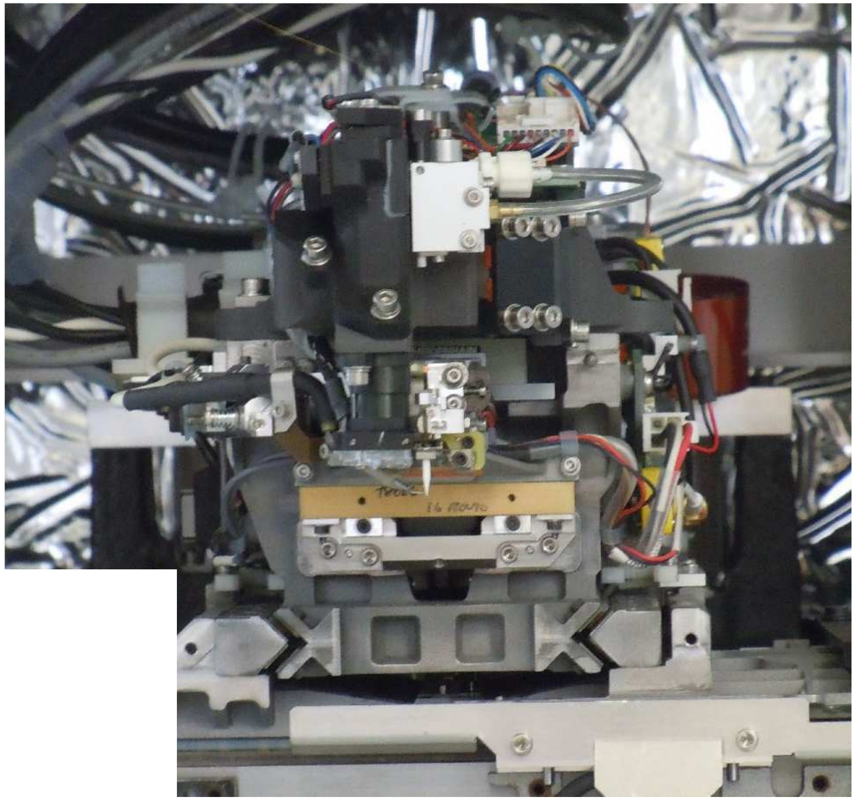
DATACON 2200 EVO BONDING SYSTEM

- Accuracy: 7 µm
- Working area sufficient for modules
- No inert / reducing athmosphere

Au-stud bumping system with 20 bumps per second is available

ICONN WIRE BONDING SYSTEM





Gold wire stud bonder

- 30 µm Au wire
- 65 µm capillary
- ~70 µm bump size

(processed on Hamamatsu sensor dummies)

Wedge bonding system is available

HESSE & KNIPPS BONDJET 750 M

- 360° bonding path directions
- Wedge – wedge bonding only
- Large working area

Stencil printing is also used for metal deposition on ceramic substrates

EKRA SCREEN PRINTING SYSTEM

Metal deposition via screen printing

- Select solder paste according to substrate and needed metal
- Deposite solder paste
- Anneal in oven

KIT built a ROC test setup with Peltier cooling stage

PICTURE OF KIT ROC TEST SETUP